

L Number	Hits	Search Text	DB	Time stamp
3	141713	semiconductor and bit line and contact and etch\$ and gate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 16:48
4	95906	(semiconductor and bit line and contact and etch\$ and gate) and (opening or hole or via or window)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 16:49
5	17698	((semiconductor and bit line and contact and etch\$ and gate) and (opening or hole or via or window)) and photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 16:49
6	12044	((((semiconductor and bit line and contact and etch\$ and gate) and (opening or hole or via or window)) and photoresist) and gate and source and drain	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 16:50
7	11179	((((semiconductor and bit line and contact and etch\$ and gate) and (opening or hole or via or window)) and photoresist) and gate and source and drain) and mask\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 16:50
8	2576	(((((semiconductor and bit line and contact and etch\$ and gate) and (opening or hole or via or window)) and photoresist) and gate and source and drain) and mask\$) and bpsg	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 16:51
9	1369	(((((semiconductor and bit line and contact and etch\$ and gate) and (opening or hole or via or window)) and photoresist) and gate and source and drain) and mask\$) and bpsg) and (bit adj line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 16:52